



Material Content Data Sheet



Sales Product Name	TLD5541-1QV			Issued	19. January 2018			
MA#	MA001680142							
Package	PG-VQFN-48-31			Weight*	129.25 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.790	1.39	1.39	13851	13851
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		139	
	non noble metal	zinc	7440-66-6	0.072	0.06		554	
	non noble metal	iron	7439-89-6	1.433	1.11		11088	
wire	non noble metal	copper	7440-50-8	58.193	45.02	46.20	450232	462013
	non noble metal	copper	7440-50-8	0.577	0.45	0.45	4464	4464
	encapsulation	organic material	carbon black	1333-86-4	0.190	0.15		1470
	plastics	epoxy resin	-	8.042	6.22		62221	
	inorganic material	silicondioxide	60676-86-0	55.092	42.62	48.99	426235	489926
leadfinish	non noble metal	tin	7440-31-5	2.596	2.01	2.01	20088	20088
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4749	4749
glue	plastics	epoxy resin	-	0.146	0.11		1129	
	noble metal	silver	7440-22-4	0.489	0.38	0.49	3780	4909
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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